CD54AC02...F PACKAGE CD74AC02...E OR M PACKAGE

(TOP VIEW)

1Y

1A [

2Y 🛛

2A 🛛 5

2B 🛛 6

GND 7

1B 🛛 3

2

4

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14 VCC

13 🛛 4Y

12 4B

11 🛛 4A

10 3Y

9 🛛 3B

8 🛛 3A

- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply Voltage
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ±24-mA Output Drive Current
 Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

description

The 'AC02 devices contain four independent 2-input NOR gates that perform the Boolean function $Y = \overline{A} \cdot \overline{B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

т _А	PAC	KAGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING						
	PDIP – E	Tube	CD74AC02E	CD74AC02E						
–55°C to 125°C	SOIC – M	Tube	CD74AC02M	AC02M						
-55°C to 125°C	30IC – M	Tape and reel	CD74AC02M96	ACUZIVI						
	CDIP – F	Tube	CD54AC02F3A	CD54AC02F3A						

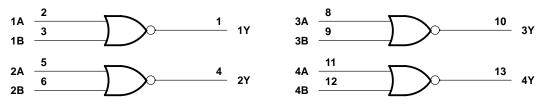
ORDERING INFORMATION

⁺ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each gate)

INP	UTS	OUTPUT
Α	В	Y
Н	Х	L
Х	Н	L
L	L	н

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 6 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 2): E package	80°C/W
M package	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			T _A = 25°C		–40°C TO 85°C		–55°C TO 125°C		UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX		
VCC	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V	
		V _{CC} = 1.5 V	1.2		1.2		1.2			
VIH High-level input voltage	High-level input voltage	VCC = 3 V	2.1		2.1		2.1		V	
		V _{CC} = 5.5 V	3.85		3.85		3.85			
		V _{CC} = 1.5 V		0.3		0.3		0.3		
VIL	Low-level input voltage	VCC = 3 V		0.9		0.9		0.9	V	
		V _{CC} = 5.5 V		1.65		1.65		1.65		
VI	Input voltage		0	VCC	0	VCC	0	VCC	V	
VO	Output voltage		0	VCC	0	VCC	0	VCC	V	
IОН	High-level output current	V_{CC} = 4.5 V to 5.5 V		-24		-24		-24	mA	
IOL	Low-level output current	V_{CC} = 4.5 V to 5.5 V		24		24		24	mA	
A+/A\/	Input transition rise or fall rate	V_{CC} = 1.5 V to 3 V		50		50		50	ns/V	
Δt/Δv In		V_{CC} = 3.6 V to 5.5 V		20		20		20	115/ V	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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PARAMETER	TEST C	TEST CONDITIONS			TEST CONDITIONS V _{CC}		T _A = 25°C		–40°C TO 85°C		–55°C TO 125°C		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX				
			1.5 V	1.4		1.4		1.4					
		I _{OH} = -50 μA	3 V	2.9		2.9		2.9					
			4.5 V	4.4		4.4		4.4					
VOH	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.48		2.4		V			
		I _{OH} = -24 mA	4.5 V	3.94		3.8		3.7					
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V					3.85					
		I _{OH} = -75 mA†	5.5 V			3.85							
			1.5 V		0.1		0.1		0.1				
		I _{OL} = 50 μA	3 V		0.1		0.1		0.1				
			4.5 V		0.1		0.1		0.1				
VOL	$V_I = V_{IH} \text{ or } V_{IL}$	I _{OL} = 12 mA	3 V		0.36		0.44		0.5	V			
		I _{OL} = 24 mA	4.5 V		0.36		0.44		0.5				
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V						1.65				
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V				1.65						
lj	$V_I = V_{CC}$ or GND		5.5 V		±0.1		±1		±1	μA			
ICC	$V_I = V_{CC}$ or GND,	I ^O = 0	5.5 V		4		40		80	μA			
Ci					10		10		10	pF			

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 1.5 \text{ V}$, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–40°C 85°C		–55°C 125	UNIT	
			MIN	MAX	MIN	MAX	
^t PLH	A or B	V		131		144	20
^t PHL	AUB	T		131		144	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	PARAMETER FROM (INPUT)			с то °С	–55°C 125	UNIT	
		(OUTPUT)	MIN	MAX	MIN	MAX	
^t PLH	A or B	V	4.1	14.6	4	16.1	-
^t PHL	AUB	Т	4.1	14.6	4	16.1	ns



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

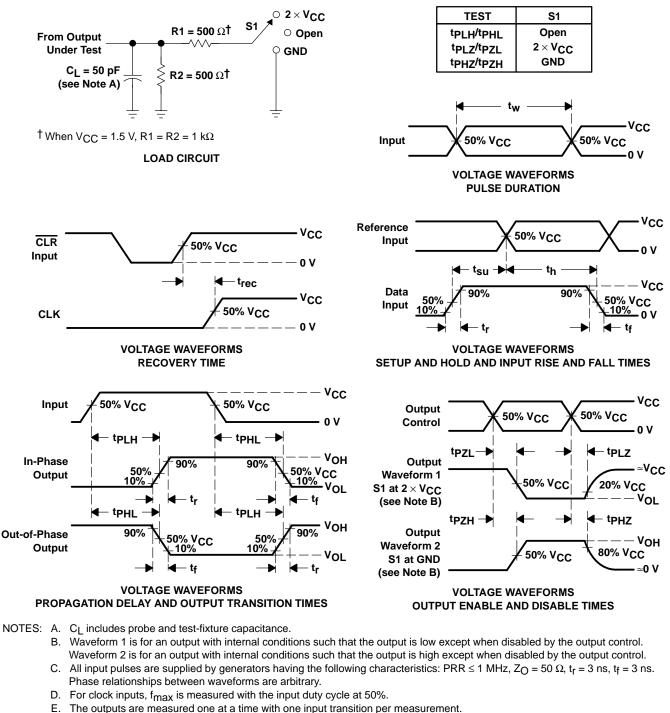
PARAMETER	FROM (INPUT)	TO (OUTPUT)	–40°C 85°		–55°C 125	-	UNIT
		(001101)	MIN	MAX	MIN	MAX	
^t PLH	A or B	V	3	10.4	2.9	11.5	
^t PHL	AOLP	Ĭ	3	10.4	2.9	11.5	ns

operating characteristics, V_{CC} = 5 V, T_A = 25° C

PARAMETER	TYP	UNIT
C _{pd} Power dissipation capacitance	55	рF

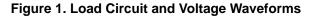


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PARAMETER MEASUREMENT INFORMATION

- F. tPLH and tPHL are the same as tpd.
- G. tp71 and tp7H are the same as ten.
- H. tpLz and tpHz are the same as tdis.







24-Aug-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
CD54AC02F3A	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD54AC02F3A	Samples
CD74AC02E	ACTIVE	PDIP	Ν	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC02E	Samples
CD74AC02EE4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC02E	Samples
CD74AC02M	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC02M	Samples
CD74AC02M96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC02M	Samples
CD74AC02ME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC02M	Samples
CD74AC02MG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC02M	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

24-Aug-2018

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD54AC02, CD74AC02 :

- Catalog: CD74AC02
- Military: CD54AC02

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions a	are nominal
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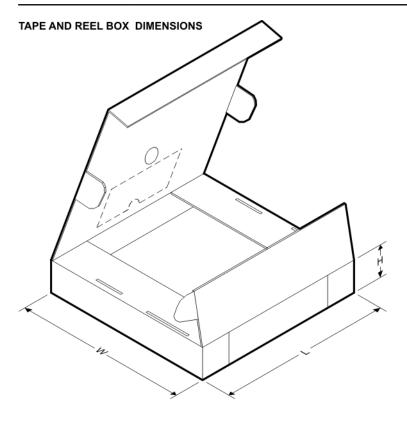
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	· /	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC02M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

26-Jan-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC02M96	SOIC	D	14	2500	367.0	367.0	38.0

GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



J0014A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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